

**B.Tech. – VIEP – ELECTRONICS AND
COMMUNICATION ENGINEERING (BTECVI)**

Term-End Examination

00706

June, 2016

BIELE-007 : NANO-ELECTRONICS

Time : 3 hours

Maximum Marks : 70

*Note : Attempt any **seven** questions. All questions carry equal marks. Use of scientific calculator is allowed. Missing data, if any, may be suitably assumed.*

1. (a) What are the challenges of nano scale MOSFETs in sub-100 nm dimensions ?
- (b) What is a technology node ? How is it defined ?
- (c) What is beyond CMOS ?
- (d) What are the interconnect issues in VLSI circuits ?

$$4 \times 2 \frac{1}{2} = 10$$

2. (a) How does oxide layer thickness play an important role in MOSFET operation ? 3
- (b) What do you mean by non-uniform dopant concentration in MOSFET technology ? 3
- (c) What is lithography and what is its role in IC fabrication technology ? Explain with a suitable diagram. 4
3. (a) Explain the operation principle of MOSFET using an energy-band diagram in all modes of operation. 5
- (b) Derive the expression for threshold voltage of MOSFETs. 5
4. (a) What is technology scaling ? How do the dimensions of MOSFETs scale down under constant field scaling ? 3
- (b) What is oxide breakdown ? How does it happen ? 3
- (c) What is velocity saturation ? Explain with a suitable diagram. 4

5. (a) Explain the Silicon-On-Insulator (SOI) technology. How is it different from bulk MOSFET technology? 5
- (b) Explain the operation principle of FinFET with its characteristics graph. 5
6. (a) What do you mean by quantum well, quantum wire and quantum dots? Explain each with its operation principle. 5
- (b) Explain the operation principle of a single electron device. Differentiate between charge quantization and energy quantization. 5
7. (a) What is the difference between Homojunction and Heterojunction based devices? Explain with suitable examples. 5
- (b) Explain the different types of heterojunction based devices with their energy band diagrams. 5
8. (a) What are the unit processes of Nano-electronics device fabrication? Show the fabrication flow of basic NMOS device. 5
- (b) What are the differences between Coulomb blockade and Coulomb staircase? 5

9. (a) Explain the operation principle of a CNFET by using suitable characteristics graphs. What is its use in electronic circuits? 5
- (b) Which semiconductor materials are very useful for spin controlled device operation? How is spin useful for the operation of SpinFETs? 5
10. Write short notes on any *two* of the following : $2 \times 5 = 10$
- (a) Heterojunction FET (HFET)
- (b) Silicon-On-Nothing
- (c) Strained Silicon
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